



DECLARATION OF JOINT INVENTORS FOR PATENT APPLICATION

1 As the below named inventor, I hereby declare that:

2
3 My residence, post office address and citizenship are as stated
4 below next to my name.

5 I believe I am the original, first and joint inventor of the subject
6 matter which is claimed and for which a patent is sought on the
7 invention entitled: Methods of Removing at Least Some of a Material
8 from a Semiconductor Substrate, filed August 31, 2000, as Application
9 Serial No. 09/653,157.

10 I hereby state that I have reviewed and understand the contents
11 of the above-identified specification, including the claims.

12 I acknowledge the duty to disclose information known to me to be
13 material to patentability as defined in Title 37, Code of Federal
14 Regulations §1.56.

PRIOR FOREIGN APPLICATIONS:

15
16 I hereby state that no applications for foreign patents or inventor's
17 certificates have been filed prior to the date of execution of this
18 declaration.

19 I hereby declare that all statements made herein of my own
20 knowledge are true and that all statements made on information and
21 belief are believed to be true; and further that these statements were
22 made with the knowledge that willful false statements and the like so

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made are punishable by fine or imprisonment, or both, under
Section 1001 of Title 18 of the United States Code and that such willful
false statement may jeopardize the validity of the application or any
patent issued therefrom.

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Full name of inventor: **Kevin J. Torek**

Inventor's Signature: *Kevin J. Torek*

Date: 11-20-00

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* * * * *

Full name of inventor: **Garo J. Derderian**

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